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Nota di contenuto	11th International Congress Molded Interconnect Devices - Scientific Proceedings; Preface and Committees; Table of Contents; Chapter 1: Development and Prototyping; Method for the Identification and Comparison of Alternative Process Chains Focusing on Economics Efficiency Analysis during the Conceptual Design of Mechatronic Integrated Devices; Novel Approach for the Implementation of 3D-MID Compatible Routing Functionalities into Computer-Aided Design Tools; Optimized Process Sequences for Prototyping of Molded Interconnect Devices; Integration of Functional Circuits into FDM Parts Chapter 2: Printing TechnologiesPrinting of Functional Structures on Molded 3D Devices; Electrical Functionalization of Thermoplastics by Combining Plasmadust Coating and Aerosol Jet Printing; Production of Miniaturized Sensor Structures on Polymer Substrates Using Inkjet Printing; Progress in the Manufacturing of Molded Interconnected Devices by 3D Microcontact Printing; Chapter 3: Materials and Manufacturing; Characterization of Electromagnetic Properties of MID

Materials for High Frequency Applications up to 67 GHz
Novel Laser Induced Metallization for Three Dimensional Molded Interconnect Device Applications by Spray MethodExperimental Investigation of Laser Sintering of Conductive Adhesive for Functional Prototypes Produced by Embedding Stereolithography; MID Fabricated by Ultrasonic Processing; Usage of Industrial Robots as Flexible Handling Devices Supporting the Process of Three Dimensional Conductive Pattern Generation; Chapter 4: Manufacturing Processes; Study of MID Technologies for Automotive Lighting and Light Signaling Devices; Chapter 5: Assembly Technologies and Inspection
Design and Solder Process Optimization in MID Technology for High Power ApplicationsChapter 6: Quality and Reliability; Hot Pin Pull Method - New Test Procedure for the Adhesion Measurement for 3D-MID; Keywords Index; Authors Index

Sommario/riassunto

Collection of selected, peer reviewed papers from the 11 th International Congress Molded Interconnect Devices (MID 2014), September 24-25, 2014, Nuremberg / Fuerth, Germany. The 16 papers are grouped as follows: Chapter 1: Development and Prototyping, Chapter 2: Printing Technologies, Chapter 3: Materials and Manufacturing, Chapter 4: Manufacturing Processes, Chapter 5: Assembly Technologies and Inspection, Chapter 6: Quality and Reliability.